Amendments to the Claims:

This listing of claims will replace all prior versions, and listing, of claims in the

application:

Listing of Claims:

Claim 1 (currently amended): An air bridge produced by:

depositing one or more circuit components on a substrate;

depositing a sacrificial material over at least a portion of the circuit

components;

depositing a crossover circuit trace of uniform composition over the sacrificial

material, the crossover circuit trace i) conforming to the sacrificial material, and ii)

crossing over the circuit components; and

thermally decomposing the sacrificial material.

Claim 2 (withdrawn): The air bridge of claim 1, wherein depositing a sacrificial

material comprises depositing the sacrificial material in a manner causing the

sacrificial material to be dome shaped.

Claim 3 (original): The air bridge of claim 1, wherein the sacrificial material

comprises polynorbornene.

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Claim 4 (original): The air bridge of claim 1, wherein the one or more circuit components comprise a circuit trace.

Claim 5 (original): The air bridge of claim 4, wherein the circuit trace comprises a signal trace.

Claim 6 (original): The air bridge of claim 4, wherein the circuit trace comprises a ground trace.

Claim 7 (original): The air bridge of claim 4, wherein the circuit trace comprises a power trace.

Claim 8 (original): The air bridge of claim 1, wherein the crossover circuit trace comprises a signal trace.

Claims 9 – 20 (canceled)

Claim 21 (currently amended): An air bridge produced by:

depositing one or more circuit components on a substrate;

depositing a sacrificial material over at least a portion of the circuit components;

depositing a crossover circuit trace of uniform composition over the sacrificial material, the crossover circuit trace i) conforming to the sacrificial material, ii)

crossing over the circuit components-and, and iii) being directly supported by the

substrate on opposite sides of the sacrificial material; and

thermally decomposing the sacrificial material.

Claim 22 (withdrawn): The air bridge of claim 21, wherein depositing a sacrificial

material comprises depositing the sacrificial material in a manner causing the

sacrificial material to be dome shaped.

Claim 23 (previously presented): The air bridge of claim 21, wherein the sacrificial

material comprises polynorbornene.

Claim 24 (previously presented): The air bridge of claim 21, wherein the one or more

circuit components comprise a circuit trace.

Claim 25 (previously presented): The air bridge of claim 24, wherein the circuit trace

comprises a signal trace.

Claim 26 (previously presented): The air bridge of claim 24, wherein the circuit trace

comprises a ground trace.

Claim 27 (previously presented): The air bridge of claim 24, wherein the circuit trace

comprises a power trace.

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Claim 28 (previously presented): The air bridge of claim 21, wherein the crossover circuit trace comprises a signal trace.